



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## DA3X101J0L

Silicon epitaxial planar type

For high speed switching circuits  
 DA3J101J in Mini3 type package

### ■ Features

- Small reverse current IR
- Short reverse recovery time trr
- Halogen-free / RoHS compliant  
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

### ■ Marking Symbol: 11

### ■ Basic Part Number :

2 elements anode-common type

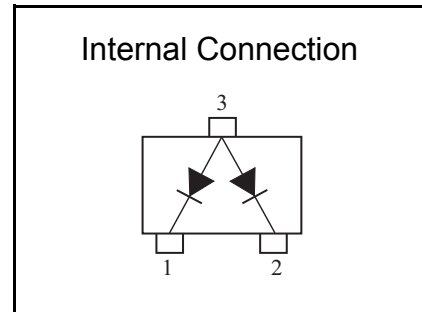
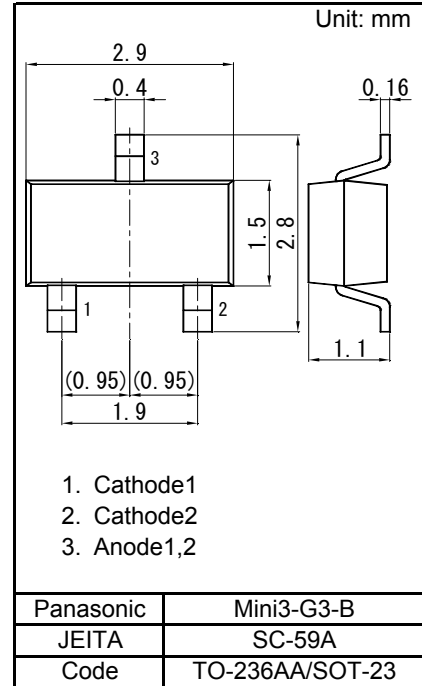
### ■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	80	V
Maximum peak reverse voltage	VRM	80	V
Forward current	Single	100	mA
	Double	150	
Peak forward current	Single	225	mA
	Double	340	
Non-repetitive peak forward surge current *1	Single	500	mA
	Double	750	
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) \*1: t = 1 s

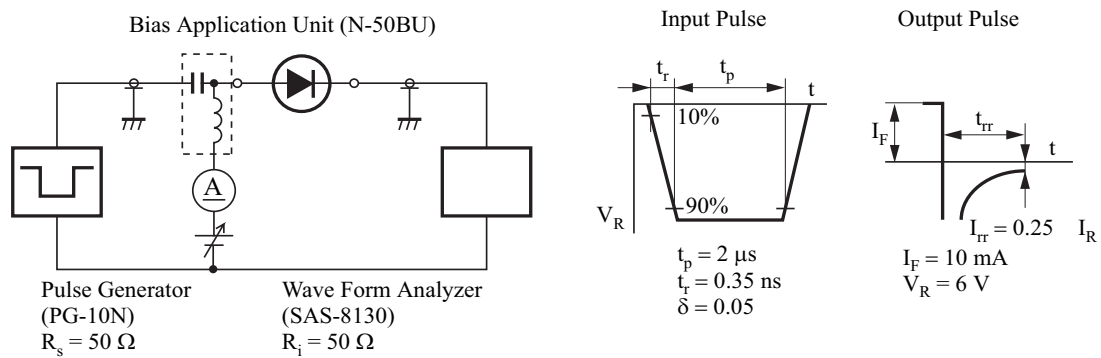




■ Electrical Characteristics  $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

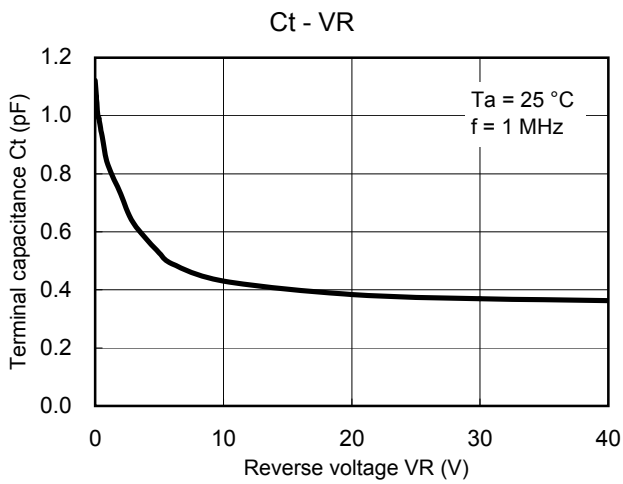
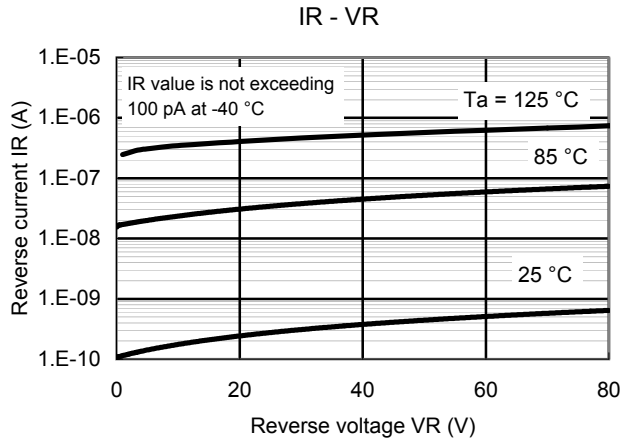
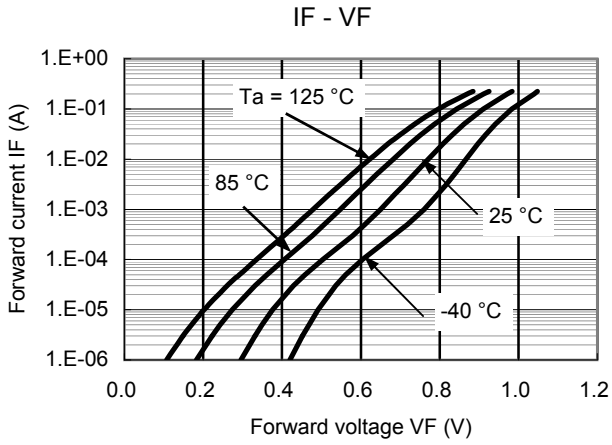
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 100 mA			1.2	V
Reverse voltage	VR	IR = 100 $\mu$ A	80			V
Reverse current	IR	VR = 80 V			100	nA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz			2	pF
Reverse recovery time *1	t <sub>rr</sub>	IF = 10mA, VR = 6V I <sub>rr</sub> = 0.25 x IR			3	ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.  
 2. Absolute frequency of input and output is 100 MHz.  
 3. \*1: t<sub>rr</sub> test circuit





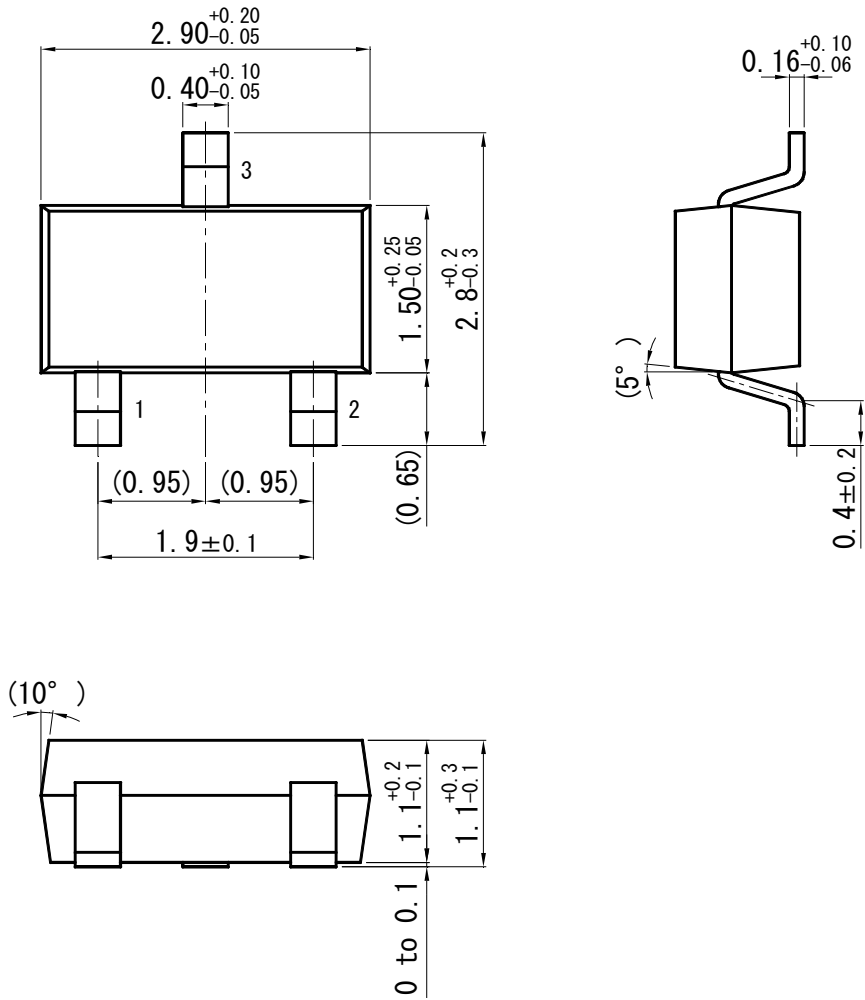
Technical Data ( reference )



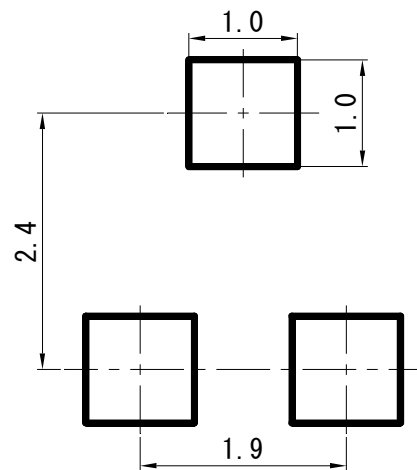


### Mini3-G3-B

Unit: mm



#### ■ Land Pattern (Reference) (Unit: mm)



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